

# EIC 2800 SEARCH REPORT



**STIC Database Tracking Number: 302513**

**To: JOSE DEES  
Location: JEF-8D59  
Art Unit: 2800  
Monday, July 20, 2009**

**Case Serial Number: 10/761098**

**From: DIANE JACKSON  
Location: EIC2800  
JEF-4B68  
Phone: (571)272-3260**

**diane.jackson@uspto.gov**

## **Search Notes**

**Attached are litigation search results in Lexis Nexis, and CourtLink and Questel-Orbit.**

**No Litigation was found for Serial Number 10/761098.**

**If you have any questions, please feel free to contact me.**

**Thanks,**

**Diane**

Jackson, Diane

JUL 20 2009

3 02513

**From:** Dees, Jose

**Sent:** Monday, July 20, 2009 11:52 AM

**To:** STIC-EIC2800

**Subject:** Reissue 10/761098

Please do a litigation search for these related patents. 6,081,029 and 6,455,348. Thanks.

*Jose' G. Dees*

Jose' G. Dees

T-QAS, TC 2800

571-272-1569

7/20/2009

Selected file: PLUSPAT

PLUSPAT - (c) Questel , All Rights Reserved  
RELOADED 04/2009 Comprehensive Worldwide Patents database  
Individual records with all stages for each Country or Patent Office  
Coverage: 85+ patenting authorities; start dates vary from 1800 forward  
Abstracts & Titles in English , French , German & various other languages  
Option to exclude Machine Transl Abs from search with /NOMT qualifier.  
For more reload details , see the PlusPat Fact Sheet and Questel website  
Last update of file: 2009/07/17 (YYYY/MM/DD) 2009-29/UP (last update)

Search statement 1

---

nbr /pn us6081029

PLUSPAT1	US6081025	1
PLUSPAT2	US6081026	1
PLUSPAT3	US6081027	1
PLUSPAT4	US6081028	1
PLUSPAT5	US6081029	1
PLUSPAT6	US608103	1
PLUSPAT7	US6081030	1
PLUSPAT8	US6081031	1
PLUSPAT9	US6081032	1
PLUSPAT10	US6081033	1
PLUSPAT11	US6081034	1
PLUSPAT12	US6081035	1
PLUSPAT13	US6081036	1
PLUSPAT14	US6081037	1
PLUSPAT15	US6081038	1

Some: numbers / Continue: Y / None: N

---

Search 1 - 5 - 1

\*\* SS 1: Results 1

Continue: Y / N

---

Search 1 - prt full legalall max - 1

\*\* SS 1: Results 1

Select All | Unselect All

☐ 1 / 1 PLUSPAT - Worldwide Patents -  
©Questel




US6081029 (A) Resin encapsulated semiconductor device having a reduced thickness and im...

PN US6081029 A 20000627 [US6081029]

TI (A) Resin encapsulated semiconductor device having a reduced thickness and improved reliability

PA (A) MATSUSHITA ELECTRONICS CORP (JP)

PAO Matsushita Electronics Corporation, Osaka [JP]  
 IN (A) YAMAGUCHI YUKIO (JP)  
 AP US24407499 19990204 [1999US-0244074]  
 PR JP6081198 19980312 [1998JP-0060811]  
 IC (A) H01L-023/28 H01L-023/36 H01L-023/495 H01L-023/50  
 H01L-023/50 [2006-01 A F I R M JP]  
 H01L-021/56 [2006-01 A - I R M EP]  
 ICAA H01L-023/12 [2006-01 A L I R M JP]  
 H01L-023/28 [2006-01 A L I R M JP]  
 H01L-023/31 [2006-01 A - I R M EP]  
 H01L-023/495 [2006-01 A - I R M EP]  
 H01L-021/02 [2006 C - I R M EP]  
 ICCA H01L-023/12 [2006 C L I R M JP]  
 H01L-023/28 [2006 C - I R M EP]  
 H01L-023/48 [2006 C - I R M EP]  
 H01L-021/56B  
 H01L-023/31H2  
 EC H01L-023/495G2  
 H01L-023/495G4  
 H01L-023/495G4B  
 PCL ORIGINAL (O) : 257718000; CROSS-REFERENCE (X) : 257E23045 257E23046 257E23047  
 257E23125 257666000 257675000 257684000 257692000 257696000 257698000 257797000  
 DT Basic  
 Unspecified source  
 US5105259 [US5105259] 257667000  
 US5157480 [US5157480] 361424000  
 US5172214 [US5172214] 257676000  
 US5225897 [US5225897] 257787000  
 US5381042 [US5381042] 257712000  
 CT US5521429 [US5521429] 257676000  
 US5641987 [US5641987] 257675000  
 US5652461 [US5652461] 257675000  
 US5731632 [US5731632] 257717000  
 US5835988 [US5835988] 257684000  
 US5872395 [US5872395] 257675000  
 US5900676 [US5900676] 257787000  
 STG (A) Patent  
 A lead frame including signal-connecting leads, a die pad and support leads is provided. A semiconductor chip is bonded to the die pad with an adhesive. The semiconductor chip, electrode pads and the signal-connecting leads are electrically connected to each other with metal fine wires. And these members are encapsulated in a resin encapsulant. The back surface of the die pad is subjected to half etching or the like to form a convex portion and a flange portion surrounding the convex portion. Since a thin layer of the resin encapsulant exists under the flange portion, the resin encapsulant can hold the die pad more strongly and the moisture resistance of the device can be improved with the lower surface of the die pad protruding from the resin encapsulant. As a result, the characteristics of a resin-molded semiconductor device having a die pad exposed on the back surface of a resin encapsulant can be improved.  
 AB  
 UP 2000-26

☐ 1 / 1 LGST - Legal Status -   
©EPO

US6081029 19990204 US/ASA [NMC]ASSIGNMENTOWNER: MATSUSHITA ELECTRONICS CORPORATION, J...

PN US6081029 A 20000627 [US6081029](A) Patent

AP US24407499 19990204 [1999US-0244074]

19990204 US-API [POS; EXM]

FILING DETAILS

PUB US24407499 19990204 [1999US-0244074]

20000627 US-A [POS; EXM]

Patent

US6081029 A 20000627 [US6081029]

19990204 US/AS-A [NMC]

ASSIGNMENT

OWNER: MATSUSHITA ELECTRONICS CORPORATION, JAPAN; EFFECTIVE DATE: 19990129

ASSIGNMENT OF ASSIGNORS INTEREST;ASSIGNOR:YAMAGUCHI, YUKIO;REEL/FRAME:009753/0250

20020129 US/AS-A [NMC]

ASSIGNMENT

OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006; EFFECTIVE DATE: 20010404

CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION /AR;REEL/FRAME:012495/0898

ACT

20020129 US/AS-A [NMC]

ASSIGNMENT

OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006; EFFECTIVE DATE: 20010404

CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION;REEL/FRAME:012495/0898

20020129 US/AS-A [NMC]

ASSIGNMENT


OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., JAPAN; EFFECTIVE DATE: 20010404

CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION;REEL/FRAME:012495/0898

LEG NMC

Alive

UP 2009-18

☐ 1 / 1 CRXX - US Claims Reassignments -   
©CLAIMS/RRX

US6081029 20020129 REASSIGNEDCHANGE OF NAMEAssignor: MATSUSHITA ELECTRONICS CORPORATION...

AN 3343780

PN 6,081,029 A 20000627 [US6081029]

PA Matsushita Electronics Corp JP

PT E (Electrical)

20020129 REASSIGNED

CHANGE OF NAME

Assignor: MATSUSHITA ELECTRONICS CORPORATION DATE SIGNED: 04/04/2001

Assignee: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006 KADOMA  
ACT KADOMA CITY, OSAKA JAPAN

Reel 012495/Frame 0898

Contact: SUGHRUE MION, PLLC DAVID J. CUSHING 2100 PENNSYLVANIA AVENUE,  
N.W. SUITE 800 WASHINGTON, D.C. 20037-3213

UP 2002-28

URAS 2002-07-09

Search statement 2

---

..fi fampat

Selected file: FAMPAT

FAMPAT - (c) Questel , All Rights Reserved

RELOADED 04/2009 Searchable biblio & abstracts for all family members  
Search and display options for both FamPat & extended family definitions  
Coverage: 85+ patenting authorities; start dates vary from 1800 forward  
New user option to view Abstracts & Titles in English , French or German  
Option to exclude Machine Transl Abs from search with /NOMT qualifier.  
For more reload details , see the FamPat Fact Sheet and Questel website  
Last update of file: 2009/07/17 (YYYY/MM/DD) 2009-29/UP (last update)

Search statement 1

---

nbr /pn us6081029

FAMPAT1	US6081025	1
FAMPAT2	US6081026	1
FAMPAT3	US6081027	1
FAMPAT4	US6081028	1
FAMPAT5	US6081029	1
FAMPAT6	US608103	1
FAMPAT7	US6081030	1
FAMPAT8	US6081031	1
FAMPAT9	US6081032	1

FAMPAT10	US6081033	1
FAMPAT11	US6081034	1
FAMPAT12	US6081035	1
FAMPAT13	US6081036	1
FAMPAT14	US6081037	1
FAMPAT15	US6081038	1

Some: numbers / Continue: Y / None: N

---

Search 1 - 5 - 1

\*\* SS 1: Results 1

Continue: Y / N

---

Search 1 - prt full legalall max - 1

\*\* SS 1: Results 1

Select All | Unselect All

☐ 1 / 1 FAMPAT - Patent Families -  
©Questel



JP11260985 Resin encapsulated semiconductor device having a reduced thickness and improv...

FAN 20090100129788

JP11260985 A 19990924 [JP11260985]

PN US6081029 A 20000627 [US6081029]

JP3285815 B2 20020527 [JP3285815]

TI Resin encapsulated semiconductor device having a reduced thickness and improved reliability

PA MATSUSHITA ELECTRONICS CORP

PA0 Matsushita Electronics Corporation, Osaka [JP]

IN YAMAGUCHI YUKIO

AP 1998JP-0060811 19980312

1999US-0244074 19990204

PR 1998JP-0060811 19980312

H01L-021/02

H01L-021/56

H01L-023/12

H01L-023/28

IC H01L-023/31

H01L-023/36

H01L-023/48

H01L-023/495

H01L-023/50

H01L-023/50 [2006-01 A F I R M JP]

H01L-021/56 [2006-01 A - I R M EP]

ICAA H01L-023/12 [2006-01 A L I R M JP]

H01L-023/28 [2006-01 A L I R M JP]

H01L-023/31 [2006-01 A - I R M EP]

H01L-023/495 [2006-01 A - I R M EP]

ICCA H01L-021/02 [2006 C - I R M EP]

H01L-023/12 [2006 C L I R M JP]  
 H01L-023/28 [2006 C - I R M EP]  
 H01L-023/48 [2006 C - I R M EP]  
 H01L-021/56B  
 H01L-023/31H2  
 EC H01L-023/495G2  
 H01L-023/495G4  
 H01L-023/495G4B  
 PCL ORIGINAL (O) : 257718000; CROSS-REFERENCE (X) : 257E23045 257E23046 257E23047  
 257E23125 257666000 257675000 257684000 257692000 257696000 257698000 257797000  
 FI H01L23/50 F; H01L23/50 G; H01L23/50 R; H01L23/50 U; H01L23/28 A; H01L23/12 501T  
 4M109 AA01; 4M109 BA01; 4M109 CA01; 4M109 CA21; 4M109 DA01; 4M109 DB02; 4M109  
 FTM DB15; 4M109 DB17; 4M109 ED03; 5F067 AA03; 5F067 AA04; 5F067 BD05; 5F067 BD10;  
 5F067 BE01; 5F067 BE04; 5F067 CA04; 5F067 DC16; 5F067 DC17; 5F067 DE01; 5F067 DF16;  
 5F067 DF17; 5F067 EA02; 5F067 EA04  
 (US6081029)  
 Unspecified source  
 US5105259 [US5105259] 257667000  
 US5157480 [US5157480] 361424000  
 US5172214 [US5172214] 257676000  
 US5225897 [US5225897] 257787000  
 CT US5381042 [US5381042] 257712000  
 US5521429 [US5521429] 257676000  
 US5641987 [US5641987] 257675000  
 US5652461 [US5652461] 257675000  
 US5731632 [US5731632] 257717000  
 US5835988 [US5835988] 257684000  
 US5872395 [US5872395] 257675000  
 US5900676 [US5900676] 257787000  
 (JP11260985)  
 (A) Examiner citations - reason for refusal [19]  
 JP (A) 1988169753 [JP63169753]  
 CT JP (A) 1987254457 [JP62254457]  
 JP (A) 1992196574 [JP04196574]  
 JP (A) 1995297344 [JP07297344]  
 JP (A) 1992003450 [JP04003450]  
 JP (A) 1991214763 [JP03214763]  
 (US6081029)  
 A lead frame including signal-connecting leads, a die pad and support leads is provided. A  
 semiconductor chip is bonded to the die pad with an adhesive. The semiconductor chip, electrode  
 pads and the signal-connecting leads are electrically connected to each other with metal fine wires.  
 And these members are encapsulated in a resin encapsulant. The back surface of the die pad is  
 AB subjected to half etching or the like to form a convex portion and a flange portion surrounding the  
 convex portion. Since a thin layer of the resin encapsulant exists under the flange portion, the  
 resin encapsulant can hold the die pad more strongly and the moisture resistance of the device can  
 be improved with the lower surface of the die pad protruding from the resin encapsulant. As a  
 result, the characteristics of a resin-molded semiconductor device having a die pad exposed on the  
 back surface of a resin encapsulant can be improved.  
 OBJ



encapsulant, a method for manufacturing such a device, and a lead frame suitable for manufacturing the resin-molded semiconductor device.

In particular, the present invention relates to an improved device with a reduced thickness.

A first object of this invention is providing a resin-molded semiconductor device suppressing delamination of a die pad by making a resin encapsulant hold the pad more strongly when the lower surface of the pad is exposed on the encapsulant, and a lead frame suitable for manufacturing such a device.

A second object is providing a resin-molded semiconductor device, preventing a resin encapsulant from cracking due to penetration of water or moisture between a die pad and the encapsulant, and a lead frame suitable for manufacturing such a device.

A third object is providing a resin-molded semiconductor device that can be self-aligned with a desired position on a motherboard more accurately by using a structure where the lower surface of a die pad is exposed on the resin encapsulant, and a method for manufacturing the same.

A fourth object is providing a resin-molded semiconductor device with heat radiation characteristics improved by preventing the formation of resin burr even if the lower surface of a die pad is exposed on the encapsulant, a manufacturing method thereof, and a lead frame suitable for manufacturing such a device.

A fifth object is providing a resin-molded semiconductor device in which solder balls need not be interposed between a die pad and a heat-radiating pad, and a method for manufacturing the same.

A first lead frame according to the present invention includes:

an outer frame surrounding a region in which a semiconductor chip is mounted; a die pad formed in the region surrounded by the outer frame; a support portion for supporting the die pad by connecting the die pad to the outer frame; and signal-connecting leads connected to the outer frame.

(US6081029)

Thus, if encapsulation is performed with a seal tape adhered to the lower surface of the lead frame, then the die pad is advantageously forced into the seal tape.

In addition, since penetration of water or moisture through the back surface of the resin-molded semiconductor device can also be advantageously suppressed as described above, the second object is achieved as well.

A second resin-molded semiconductor device according to the present invention includes:

ADB a semiconductor chip having electrode pads; a die pad for supporting the semiconductor chip thereon; signal-connecting leads; connecting members for electrically connecting the electrode pads of the semiconductor chip to the signal-connecting leads; and a resin encapsulant for encapsulating the die pad, the semiconductor chip, the signal-connecting leads and the connecting members.

This is because the die pad cannot be in satisfactory contact with a heat-radiating pad in such a case.

However, such a process is not just troublesome, but causes additional problems.

Specifically, if a water jet process is carried out, then a nickel, palladium or gold plated layer might peel off and impurity might deposit on the exposed parts.

(US6081029)

1. A lead frame comprising:

an outer frame surrounding a region in which a semiconductor chip is mounted;

a die pad formed in the region surrounded by the outer frame;

support leads for supporting the die pad by connecting the die pad to the outer frame; and

ICLM signal-connecting leads connected to the outer frame,

wherein the die pad is located below the outer frame, and part of each said support lead is bent to function as a spring.

2. A lead frame comprising:

an outer frame surrounding a region in which a semiconductor chip is mounted;

a die pad formed in the region surrounded by the outer frame;

support leads for supporting the die pad by connecting the die pad to the outer frame; and signal-connecting leads connected to the outer frame, wherein the die pad is located below the outer frame, the support leads are provided between the signal-connecting leads and the die pad, and part of each said support lead is bent to function as a spring.

4. A resin-molded semiconductor device comprising:

a semiconductor chip having electrode pads;

a die pad for supporting the semiconductor chip thereon;

support leads for supporting the die pad;

signal-connecting leads;

connecting members for electrically connecting the electrode pads of the semiconductor chip to the signal-connecting leads; and

a resin encapsulant for encapsulating the die pad, the semiconductor chip, the signal-connecting leads and the connecting members,

wherein respective lower parts of the die pad and the signal-connecting leads are at least partially not covered with the resin encapsulant but exposed, and

wherein each said support lead extends from an associated corner of the die pad to reach a side face of the resin encapsulant and is partially bent to function as a spring.

6. A resin-molded semiconductor device comprising:

a semiconductor chip having electrode pads;

a die pad for supporting the semiconductor chip thereon;

support leads for supporting the die pad;


signal-connecting leads;

connecting members for electrically connecting the electrode pads of the semiconductor chip to the signal-connecting leads; and

a resin encapsulant for encapsulating the die pad, the semiconductor chip, the signal-connecting leads and the connecting members,

wherein respective lower parts of the die pad and the signal-connecting leads are at least partially not covered with the resin encapsulant but exposed, the support leads are provided between the die pad and the signal-connecting leads, and each said support lead is partially bent to function as a spring.

UP 2000-08

☐ 1 / 1 LGST - Legal Status - 

©EPO

US6081029 19990204 US/ASA [NMC]ASSIGNMENTOWNER: MATSUSHITA ELECTRONICS CORPORATION, J...

PN US6081029 A 20000627 [US6081029](A) Patent

AP US24407499 19990204 [1999US-0244074]  
19990204 US-API [POS; EXM]

FILING DETAILS

PUB US24407499 19990204 [1999US-0244074]  
20000627 US-A [POS; EXM]  
Patent

US6081029 A 20000627 [US6081029]

ACT 19990204 US/AS-A [NMC]  
ASSIGNMENT


OWNER: MATSUSHITA ELECTRONICS CORPORATION, JAPAN; EFFECTIVE DATE:  
19990129  
ASSIGNMENT OF ASSIGNORS INTEREST; ASSIGNOR: YAMAGUCHI,  
YUKIO; REEL/FRAME: 009753/0250

20020129 US/AS-A [NMC]  
ASSIGNMENT  
OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006; EFFECTIVE  
DATE: 20010404  
CHANGE OF NAME; ASSIGNOR: MATSUSHITA ELECTRONICS CORPORATION  
/AR; REEL/FRAME: 012495/0898

20020129 US/AS-A [NMC]  
ASSIGNMENT  
OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006; EFFECTIVE  
DATE: 20010404  
CHANGE OF NAME; ASSIGNOR: MATSUSHITA ELECTRONICS  
CORPORATION; REEL/FRAME: 012495/0898

20020129 US/AS-A [NMC]  
ASSIGNMENT  
OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., JAPAN; EFFECTIVE DATE:  
20010404  
CHANGE OF NAME; ASSIGNOR: MATSUSHITA ELECTRONICS  
CORPORATION; REEL/FRAME: 012495/0898

LEG NMC  
UP Alive  
2009-18

☐ 1 / 1 CRXX - US Claims Reassignments -   
©CLAIMS/RRX

US6081029 20020129 REASSIGNED CHANGE OF NAME Assignor: MATSUSHITA ELECTRONICS  
CORPORATIO...

AN 3343780  
PN 6,081,029 A 20000627 [US6081029]  
PA Matsushita Electronics Corp JP  
PT E (Electrical)  
20020129 REASSIGNED  
CHANGE OF NAME

Assignor: MATSUSHITA ELECTRONICS CORPORATION DATE SIGNED: 04/04/2001

ACT Assignee: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006 KADOMA  
KADOMA CITY, OSAKA JAPAN

Reel 012495/Frame 0898

Contact: SUGHRUE MION, PLLC DAVID J. CUSHING 2100 PENNSYLVANIA AVENUE,  
N.W. SUITE 800 WASHINGTON, D.C. 20037-3213

UP 2002-28  
URAS 2002-07-09

Search statement 2

**Single Search - with Terms and Connectors**

Enter keywords - Search multiple dockets & documents

**Search**

[View Demo](#)  
[Search Tips](#)

[My CourtLink](#)

[Search](#)

[Dockets & Documents](#)

[Track](#)

[Alert](#)

[Strategic Profiles](#)

[My Account](#)



[Search](#) > [Patent Search](#) > Searching

Patent Search 6081029 7/20/2009

No cases found.

[Return to Search](#)

(Charges for search still apply)



**LexisNexis®**

[About LexisNexis](#) | [Terms & Conditions](#) | [Pricing](#) | [Privacy](#) | [Customer Support](#) - 1-888-311-1966  
Copyright © 2009 LexisNexis®. All rights reserved.

LexisNexis® Total Research System

[Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)FOCUS™ Terms  Search Within   [Advanced...](#) Source: Combined Source Set 10 ☐ - Utility, Design and Plant PatentsTerms: Patno=6081029 ([Edit Search](#)) | ([Suggest Terms for My Search](#))

244074 (09) 6081029 June 27, 2000

## UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

**6081029**[Get Drawing Sheet 1 of 15](#)[Access PDF of Official Patent \\*](#)[Order Patent File History / Wrapper from REEDFAX®](#)[Link to Claims Section](#)

June 27, 2000

Resin encapsulated semiconductor device having a reduced thickness and improved reliability

**INVENTOR:** Yamaguchi, Yukio - Shiga, Japan (JP)**APPL-NO:** 244074 (09)**FILED-DATE:** February 4, 1999**GRANTED-DATE:** June 27, 2000**PRIORITY:** March 12, 1998 - 10060811, Japan (JP)**ASSIGNEE-PRE-ISSUE:** February 4, 1999 - ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS)., MATSUSHITA ELECTRONICS CORPORATION 1-1, SAIWAI-CHO, TAKATSUKI-SHIOSAKA 59-1193, (1), Reel and Frame Number: 009753/0250**ASSIGNEE-AT-ISSUE:** Matsushita Electronics Corporation, Osaka, Japan (JP), Foreign company or corporation (03)**ASSIGNEE-AFTER-ISSUE:** January 29, 2002 - CHANGE OF NAME (SEE DOCUMENT FOR DETAILS)., MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006 KADOMAKADOMA CITY, OSAKA, (1), Reel and Frame Number: 012495/0898**LEGAL-REP:** McDermott, Will & Emery**PUB-TYPE:** June 27, 2000 - Utility Patent having no previously published pre-grant publication (A)**PUB-COUNTRY:** United States (US)**US-MAIN-CL:** 257#718**US-ADDL-CL:** 257#666, 257#675, 257#684, 257#692, 257#696, 257#698, 257#797, 257#E23.045, 257#E23.046, 257#E23.047, 257#E23.125**CL:** 257

LexisNexis® Total Research System

[Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
by Source | by Topic or Headnote | by Guided Search Form | by Dot Command

**Combined Source Set 15** - Federal & State Cases, Combined; Federal Court Cases, Combined; State Court Cases, Combined; U.S. Supreme Court Cases, Lawyers' Edition; U.S. Supreme Court Briefs; Federal Agency Decisions, Combined; State Administrative Codes & Registers, Combined

## Search



## Enter Search Terms

☒ Terms and Connectors ☐ Natural Language ☐ Easy Search™

(6081029 or 6,081,029)

[Suggest terms  
for my search](#)

Search

[Check spelling](#)

## Restrict by Document Segment

Select a document segment, enter search terms for the segment, then click Add.

Select a Segment

Add ↑

Note: Segment availability differs between sources. Segments may not be applied consistently across sources.

## Restrict by Date

☒ No Date Restrictions☐

From

To

[Date formats...](#)

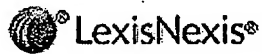
## Search Connectors

<u>and</u>	and	<u>w/p</u>	in same paragraph
<u>or</u>	or	<u>w/seg</u>	in same segment
<u>w/N</u>	within N words	<u>w/s</u>	in same sentence
<u>pre/N</u>	precedes by N words	<u>and not</u>	and not

> [More Connectors & Commands...](#)

## How Do I...?

- > [Combine sources?](#)
- > [Restrict by date?](#)
- > [Restrict by document segment?](#)
- > [Use wildcards as placeholders for one or more characters in a search term?](#)

[View Tutorials](#)[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
[Selector](#)[History](#) | [Delivery Manager](#) | [Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)[About LexisNexis](#) | [Terms & Conditions](#) | [Contact Us](#)  
Copyright © 2009 LexisNexis, a division of Reed Elsevier Inc. All rights reserved.

## No Documents Found

No documents were found for your search terms

"(6081029 or 6,081,029)"

---

Click "Edit Search" to return to the search form and modify your search.

### Suggestions:

- Check for spelling errors .
  - Remove some search terms.
  - Use more common search terms, such as those listed in "Suggested Words and Concepts"
  - Use a less restrictive date range.
- 

[Edit Search](#)



**LexisNexis®**

[About LexisNexis](#) | [Terms & Conditions](#) | [Contact Us](#)

Copyright © 2009 LexisNexis, a division of Reed Elsevier Inc. All rights reserved.



LexisNexis® Total Research System

[Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
by Source | by Topic or Headnote | by Guided Search Form | by Dot Command

**Combined Source Set 14** - Intellectual Property Cases, Administrative Decisions & Regulations; Federal Register and CFR - Titles 19 and 37; Federal Register Documents Relating To Patent Issues; U.S. Patent & Trademark Office Decisions, Combined; Intellectual Property Law Review Articles, Combined; Patent, Trademark & Copyright Periodicals, Combined; Intellectual Property Law, Combined

## Search



## Enter Search Terms

☒ Terms and Connectors ☐ Natural Language ☐ Easy Search™

(6081029 or 6,081,029)

[Suggest terms  
for my search](#)[Search](#)[Check spelling](#)

## Restrict by Document Segment

Select a document segment, enter search terms for the segment, then click Add.

Select a Segment

Add ↑

Note: Segment availability differs between sources. Segments may not be applied consistently across sources.

## Restrict by Date

☒ No Date Restrictions ☐ From  To  [Date formats...](#)

## Search Connectors

and	and	w/p	in same paragraph
or	or	w/seg	in same segment
w/N	within N words	w/s	in same sentence
pre/N	precedes by N words	and not	and not

> [More Connectors & Commands...](#)

## How Do I...?

- > [Combine sources?](#)
- > [Restrict by date?](#)
- > [Restrict by document segment?](#)
- > [Use wildcards as placeholders for one or more characters in a search term?](#)

[View Tutorials](#)[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
[Selector](#)[History](#) | [Delivery Manager](#) | [Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)

LexisNexis®

[About LexisNexis](#) | [Terms & Conditions](#) | [Contact Us](#)

Copyright © 2009 LexisNexis, a division of Reed Elsevier Inc. All rights reserved.

## No Documents Found

No documents were found for your search terms

"(6081029 or 6,081,029)"

---

Click "Save this search as an Alert" to schedule your search to run in the future.

- OR -

Click "Edit Search" to return to the search form and modify your search.

Suggestions:

- Check for spelling errors .
  - Remove some search terms.
  - Use more common search terms, such as those listed in "Suggested Words and Concepts"
  - Use a less restrictive date range.
- 

 [Save this Search as an Alert](#)

[Edit Search](#)



**LexisNexis®**

[About LexisNexis](#) | [Terms & Conditions](#) | [Contact Us](#)

Copyright © 2009 LexisNexis, a division of Reed Elsevier Inc. All rights reserved.

LexisNexis® Total Research System

[Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
by Source | by Topic or Headnote | by Guided Search Form | by Dot Command

Combined Source Set 1 - News, All (English, Full Text); Legal News Publications

## Search

## Enter Search Terms

☒ Terms and Connectors ☐ Natural Language ☐ Easy Search™

(6081029 or 6,081,029)

[Suggest terms  
for my search](#)

Search

[Check spelling](#)

## Restrict by Document Segment

Select a document segment, enter search terms for the segment, then click Add.

Select a Segment

Add

Note: Segment availability differs between sources. Segments may not be applied consistently across sources.

## Restrict by Date

☒ No Date Restrictions ☐

From

To

[Date formats...](#)

## Search Connectors

<a href="#">and</a>	and	<a href="#">w/p</a>	in same paragraph
<a href="#">or</a>	or	<a href="#">w/seg</a>	in same segment
<a href="#">w/N</a>	within N words	<a href="#">w/s</a>	in same sentence
<a href="#">pre/N</a>	precedes by N words	<a href="#">and not</a>	and not

> [More Connectors & Commands...](#)

## How Do I...?

- > [Combine sources?](#)
- > [Restrict by date?](#)
- > [Restrict by document segment?](#)
- > [Use wildcards as placeholders for one or more characters in a search term?](#)

[View Tutorials](#)[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
Selector[History](#) | [Delivery Manager](#) | [Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)

LexisNexis®

[About LexisNexis](#) | [Terms & Conditions](#) | [Contact Us](#)

Copyright © 2009 LexisNexis, a division of Reed Elsevier Inc. All rights reserved.

LexisNexis® Total Research System

[Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)FOCUS™ Terms  Search Within   [Advanced...](#) Source: Combined Source Set 1  - News, All (English, Full Text)Terms: (6081029 or 6,081,029) ([Edit Search](#) | [Suggest Terms for My Search](#))☒ Select for FOCUS™ or Delivery

- ☐ 1. The Ottawa Sun, June 8, 2000, Thursday,, Final EDITION, NEWS,, Pg. 4, 300 words, ACCUSED SAYS SEX AGREED TO, RICHARD ROIK, OTTAWA SUN
- ☐ 2. Business Wire, October 16, 1995, Monday, 1299 words, Brio Industries reports sharply improved results for second quarter and six months, VANCOUVER, British Columbia ... income taxes 1,103,916 (6,081,029) Income (taxes) recovery ( ...

Source: Combined Source Set 1  - News, All (English, Full Text)Terms: (6081029 or 6,081,029) ([Edit Search](#) | [Suggest Terms for My Search](#))

View: Cite

Date/Time: Monday, July 20, 2009 - 2:11 PM EDT

[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
[Selector](#)[History](#) | [Delivery Manager](#) | [Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)

LexisNexis®

[About LexisNexis](#) | [Terms & Conditions](#) | [Contact Us](#)

Copyright © 2009 LexisNexis, a division of Reed Elsevier Inc. All rights reserved.

LexisNexis® Total Research System

[Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)

[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)

FOCUS™ Terms  Search Within   [Advanced...](#)

Source: Combined Source Set 1  - News, All (English, Full Text)

Terms: (6081029 or 6,081,029) ([Edit Search](#) | [Suggest Terms for My Search](#))

☒ Select for FOCUS™ or Delivery



*ACCUSED SAYS SEX AGREED TO The Ottawa Sun June 8, 2000, Thursday,*

Copyright 2000 Sun Media Corporation  
The Ottawa Sun

June 8, 2000, Thursday, Final EDITION

**SECTION:** NEWS, Pg. 4

**LENGTH:** 300 words

**HEADLINE:** ACCUSED SAYS SEX AGREED TO

**BYLINE:** RICHARD ROIK, OTTAWA SUN

Source: Combined Source Set 1  - News, All (English, Full Text)

Terms: (6081029 or 6,081,029) ([Edit Search](#) | [Suggest Terms for My Search](#))

View: KWIC

Date/Time: Monday, July 20, 2009 - 2:11 PM EDT

[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
[Selector](#)

[History](#) | [Delivery Manager](#) | [Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)



LexisNexis®

[About LexisNexis](#) | [Terms & Conditions](#) | [Contact Us](#)

Copyright © 2009 LexisNexis, a division of Reed Elsevier Inc. All rights reserved.

**LexisNexis® Total Research System**

[Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)

[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)

**FOCUS™ Terms** (6081029 or 6,081,029) Search Within [Original Results \(1 - 2\)](#) [Go](#) [Advanced...](#)

[All Results - \(2\)](#) [News - \(2\)](#)

Source: **Combined Source Set 1** [1](#) - News, All (English, Full Text)

Terms: (6081029 or 6,081,029) ([Edit Search](#) | [Suggest Terms for My Search](#))

☒ Select for FOCUS™ or Delivery



*ACCUSED SAYS SEX AGREED TO The Ottawa Sun June 8, 2000, Thursday,*

Copyright 2000 Sun Media Corporation  
The Ottawa Sun

June 8, 2000, Thursday, Final EDITION

**SECTION:** NEWS, Pg. 4

**LENGTH:** 300 words

**HEADLINE:** ACCUSED SAYS SEX AGREED TO

**BYLINE:** RICHARD ROIK, OTTAWA SUN

Source: **Combined Source Set 1** [1](#) - News, All (English, Full Text)

Terms: (6081029 or 6,081,029) ([Edit Search](#) | [Suggest Terms for My Search](#))

View: KWIC

Date/Time: Monday, July 20, 2009 - 2:11 PM EDT

[My Lexis™](#) | [Search](#) | [Research Tasks](#) | [Get a Document](#) | [Shepard's®](#) | [Alerts](#) | [Total Litigator](#) | [Transactional Advisor](#) | [Counsel](#)  
[Selector](#)

[History](#) | [Delivery Manager](#) | [Switch Client](#) | [Preferences](#) | [Sign Out](#) | [Help](#)



**LexisNexis®** [About LexisNexis](#) | [Terms & Conditions](#) | [Contact Us](#)

[Copyright ©](#) 2009 LexisNexis, a division of Reed Elsevier Inc. All rights reserved.